



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 100M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受1000V AC/Minute
8. 工作温度: $-25^{\circ} \sim +85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235 \pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求。

| Part No | Pin | A | B |
|----------------------|-----|-------|-------|
| WAFER-PH2.0-2PZZ-GH | 2 | 2.00 | 6.00 |
| WAFER-PH2.0-3PZZ-GH | 3 | 4.00 | 8.00 |
| WAFER-PH2.0-4PZZ-GH | 4 | 6.00 | 10.00 |
| WAFER-PH2.0-5PZZ-GH | 5 | 8.00 | 12.00 |
| WAFER-PH2.0-6PZZ-GH | 6 | 10.00 | 14.00 |
| WAFER-PH2.0-7PZZ-GH | 7 | 12.00 | 16.00 |
| WAFER-PH2.0-8PZZ-GH | 8 | 14.00 | 18.00 |
| WAFER-PH2.0-9PZZ-GH | 9 | 16.00 | 20.00 |
| WAFER-PH2.0-10PZZ-GH | 10 | 18.00 | 22.00 |
| WAFER-PH2.0-11PZZ-GH | 11 | 20.00 | 24.00 |
| WAFER-PH2.0-12PZZ-GH | 12 | 22.00 | 26.00 |
| WAFER-PH2.0-13PZZ-GH | 13 | 24.00 | 28.00 |
| WAFER-PH2.0-14PZZ-GH | 14 | 26.00 | 30.00 |
| WAFER-PH2.0-15PZZ-GH | 15 | 28.00 | 32.00 |
| WAFER-PH2.0-16PZZ-GH | 16 | 30.00 | 34.00 |
| WAFER-PH2.0-17PZZ-GH | 17 | 32.00 | 36.00 |
| WAFER-PH2.0-18PZZ-GH | 18 | 34.00 | 38.00 |
| WAFER-PH2.0-19PZZ-GH | 19 | 36.00 | 40.00 |
| WAFER-PH2.0-20PZZ-GH | 20 | 38.00 | 42.00 |

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|---|-----------|-------------------|-----|---------------------------------------|
| 2 | 端子Contact | 黄铜 | N*1 | 电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡80u"MIN |
| 1 | 基座Wafer | PA66(UL94 V-0) | 1 | 黄色 |

| 序号 | 名称 | 材料 | 数量 | 备注 |
|----|----|----|----|----|
|----|----|----|----|----|

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|---------------------------------------|-----|--|----------------------------|---------------------|
| MANUFACTURE DWG | | 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd | | |
| UNLESS OTHERWISE SPECIFIED TOLERANCES | | | TITLE: WAFER PH2.0MM 直针 | |
| DECIMALS: | | | PAR | WAFER-PH2.0-NPZZ-GH |
| ANGLES: | | | DWN | |
| .X±0.20 | ±2' | | CHKD | |
| .XX±0.10 | | APVD | | |
| .XXX±0.05 | | SCALE:1:1 | UNIT:MM | |
| CUSTOMER COPY | | SIZE:A4 | SHEET:1F1 | REV:A |